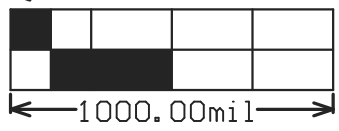
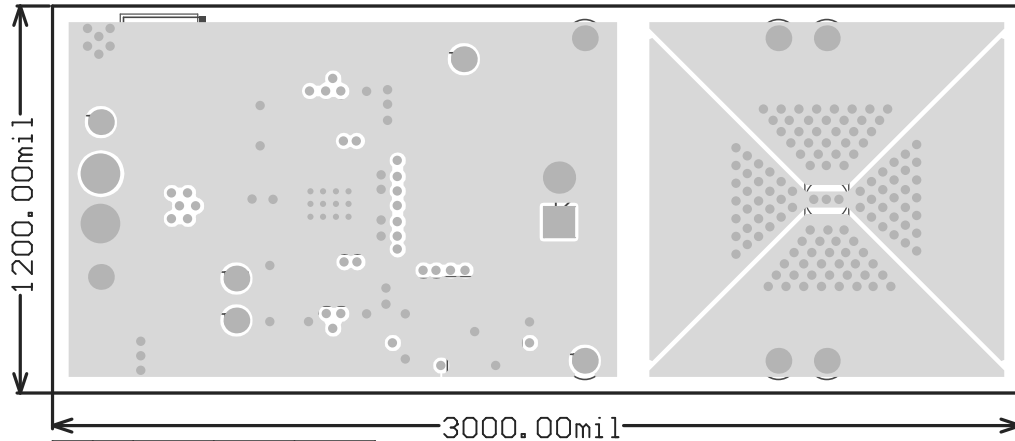


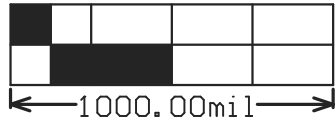
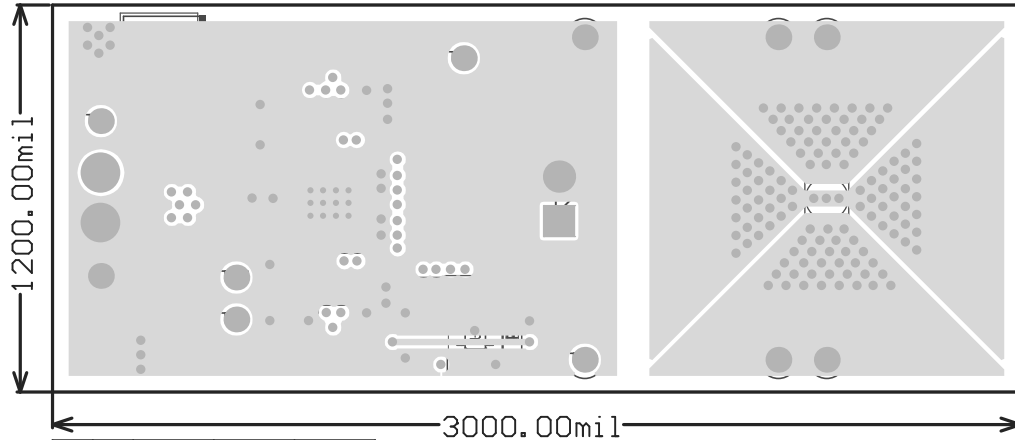
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 ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



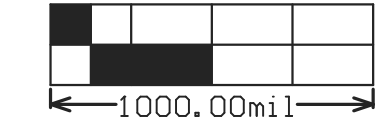
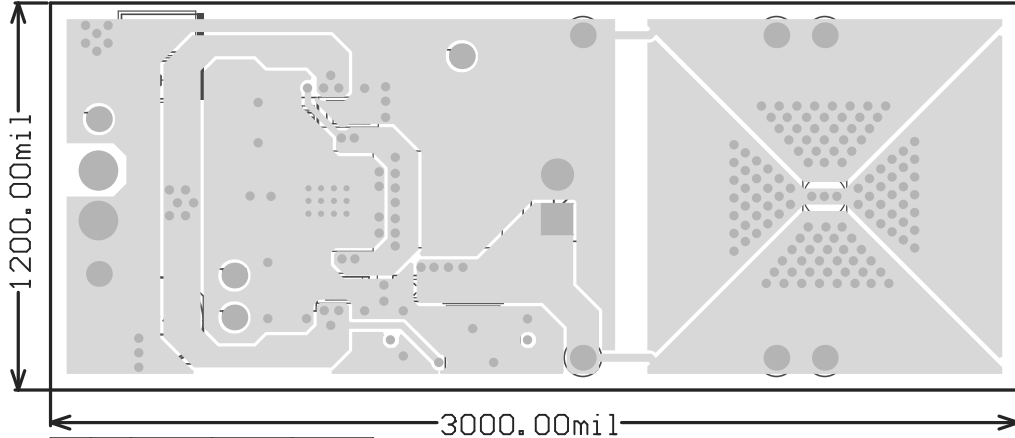
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



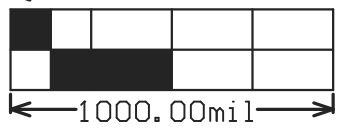
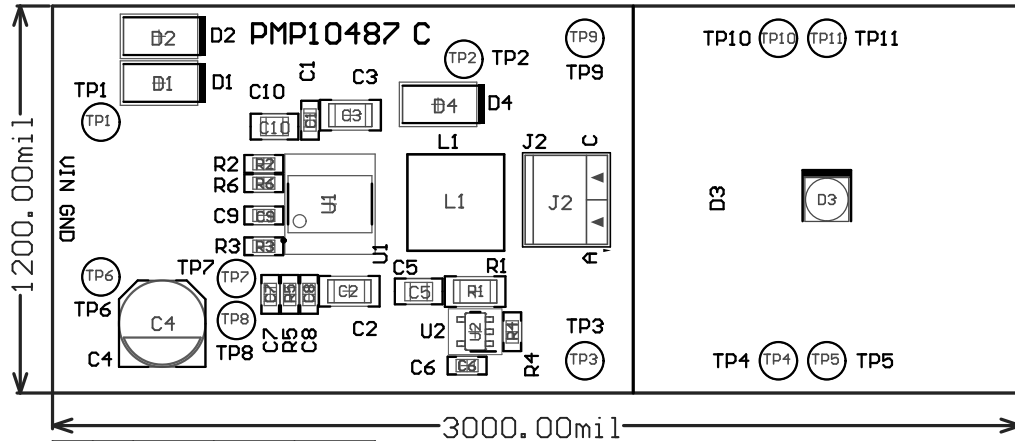
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



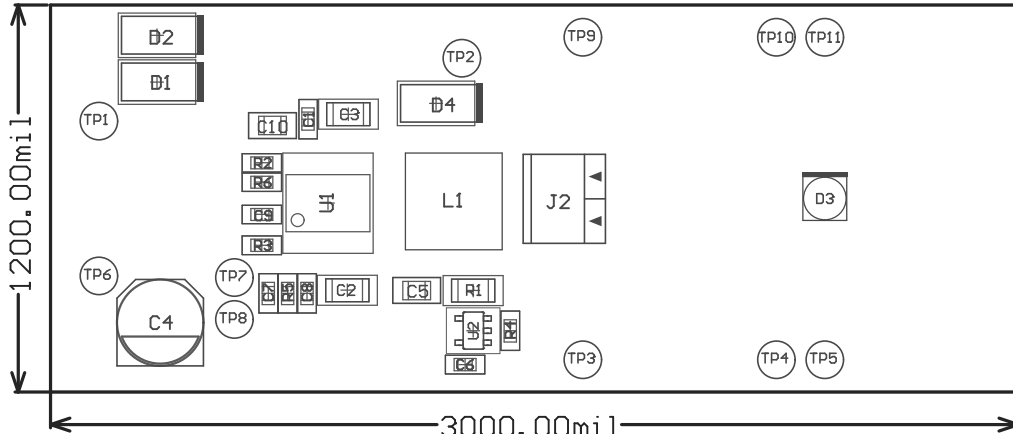
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
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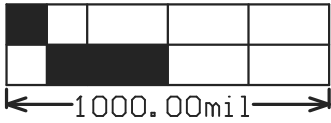
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED  
 ASSEMBLY VARIANT: [No Variations]



1200.00mil

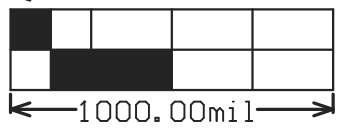
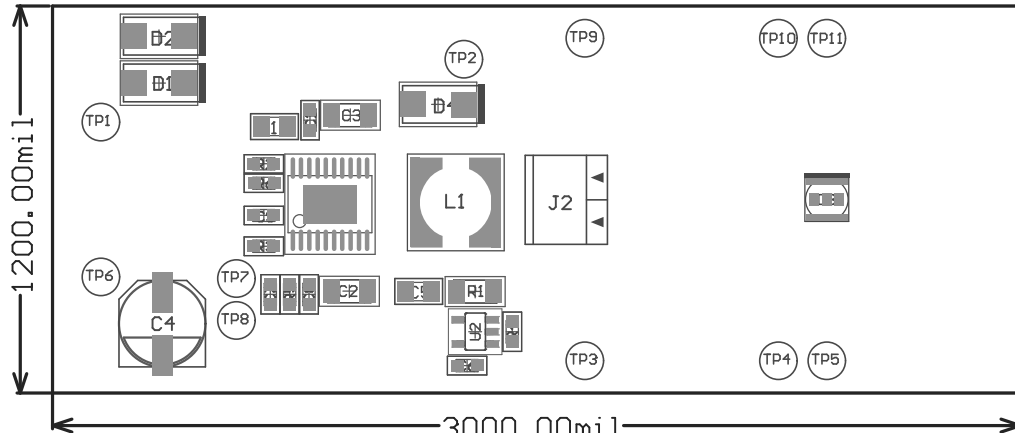
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1000.00mil

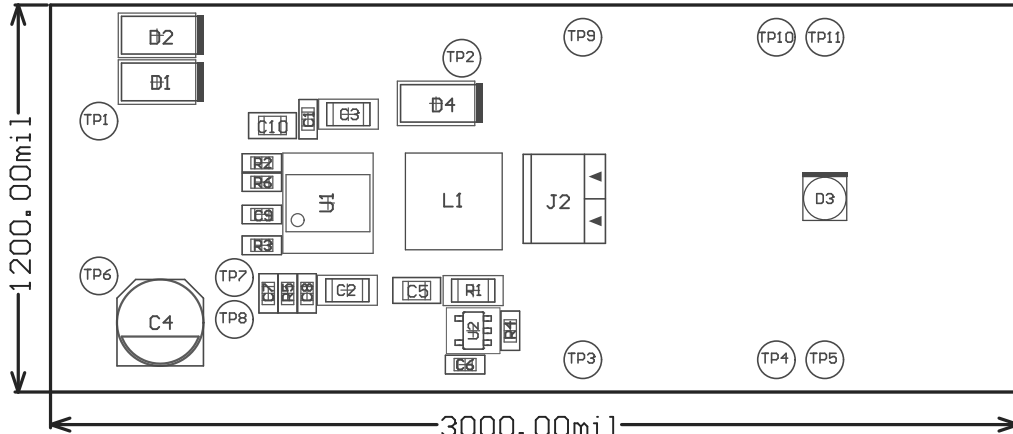
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 ASSEMBLY VARIANT: [No Variations]



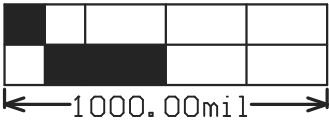
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



1200.00mil

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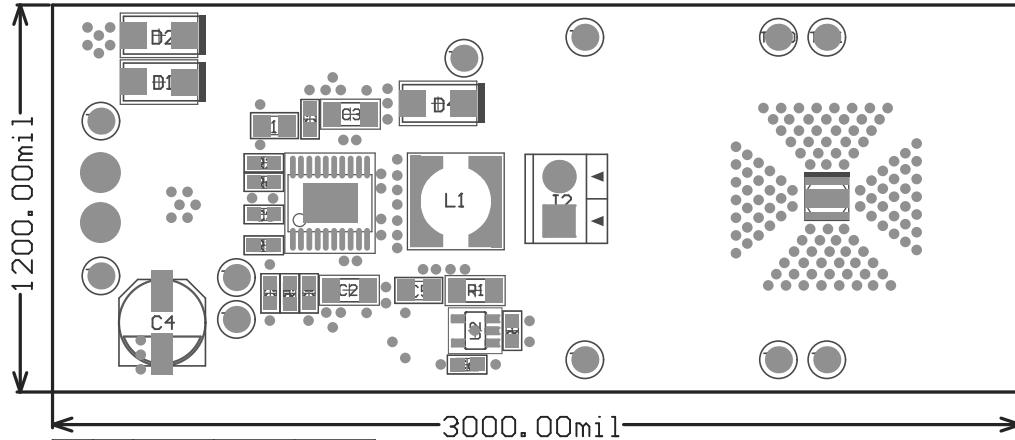


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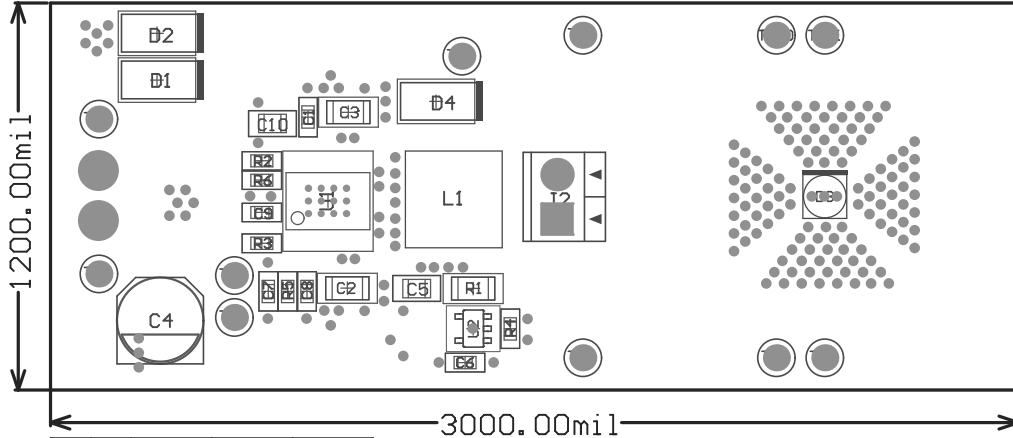
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 ASSEMBLY VARIANT: [No Variations]



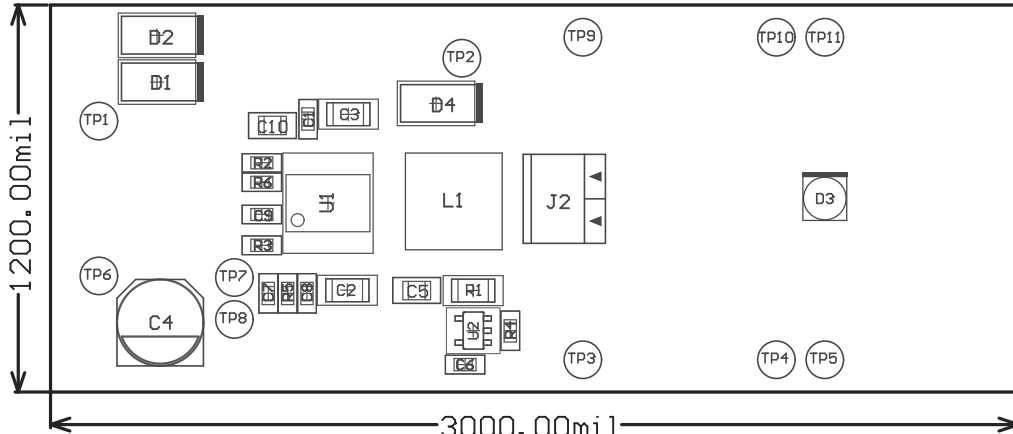


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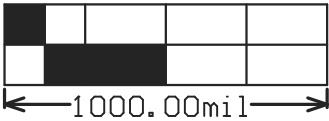


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. TOU DLUOHS 'DNP' DEKRAM STNEIOPMOO  
 ASSEMBLY VARIANT: [No Variations] [noitirv oN] :TNAIRAV YJBM32SA



1200.00mil

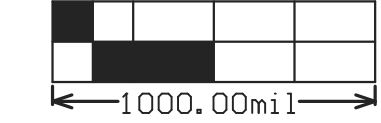
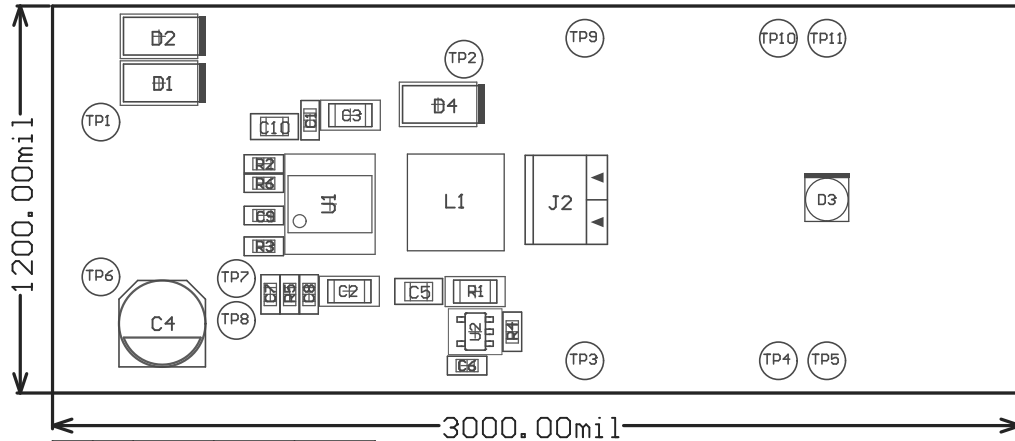
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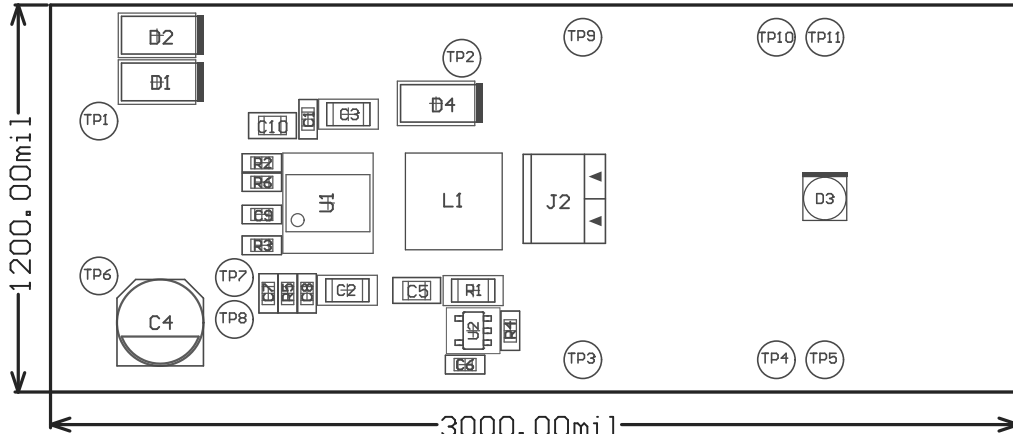
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



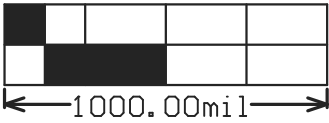
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 ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



1200.00mil

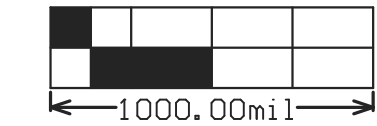
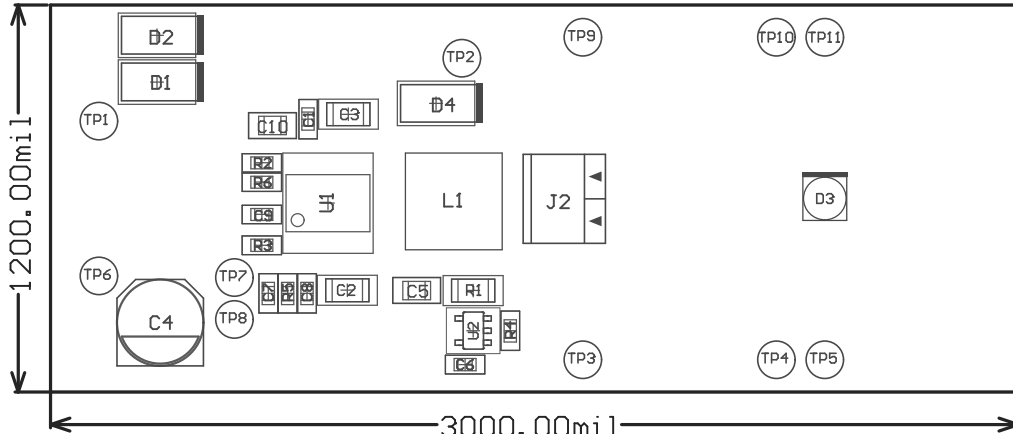
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1000.00mil

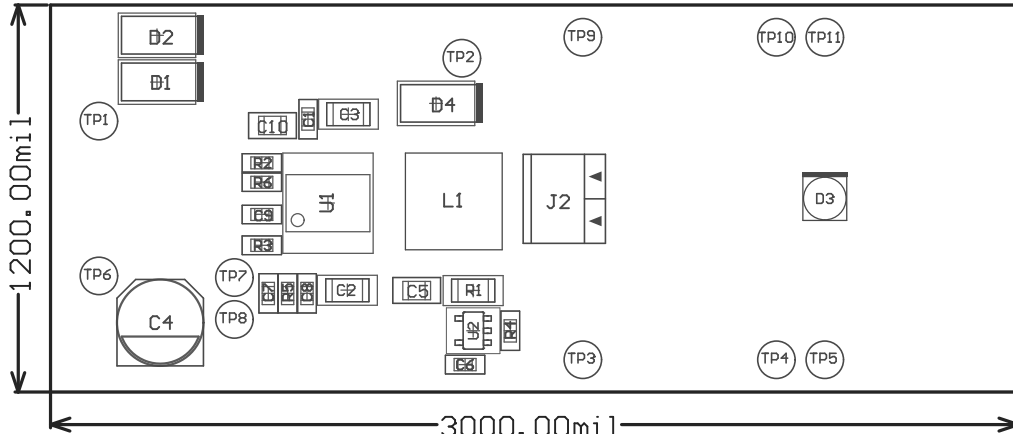
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 ASSEMBLY VARIANT: [No Variations]



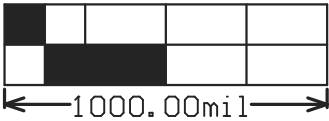
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1200.00mil

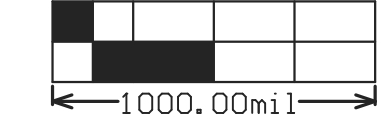
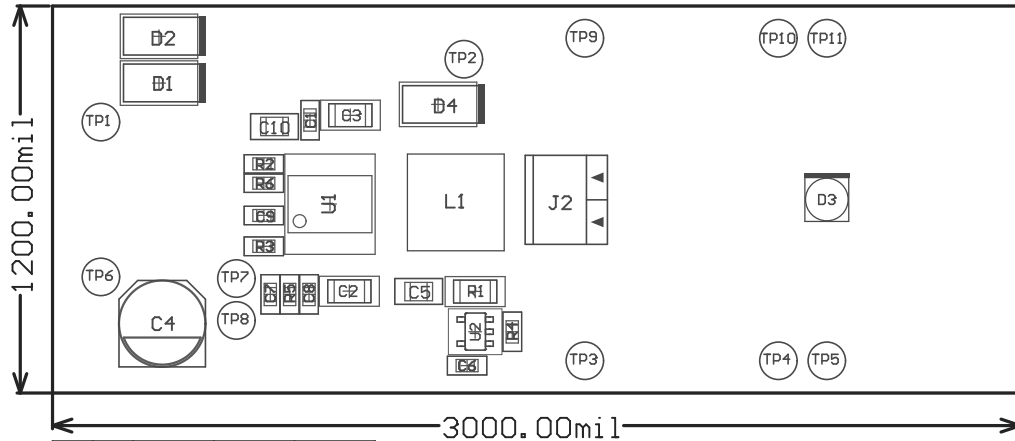
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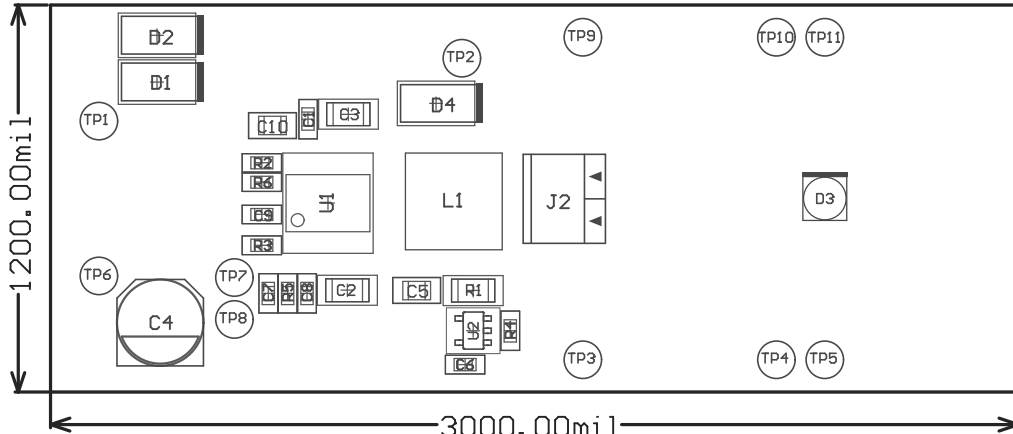
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 ASSEMBLY VARIANT: [No Variations]



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. 38 TON DJUOH2 'QND' DEKRAM 2TNEIOPMOC  
 ASSEMBLY VARIANT: [No Variations]

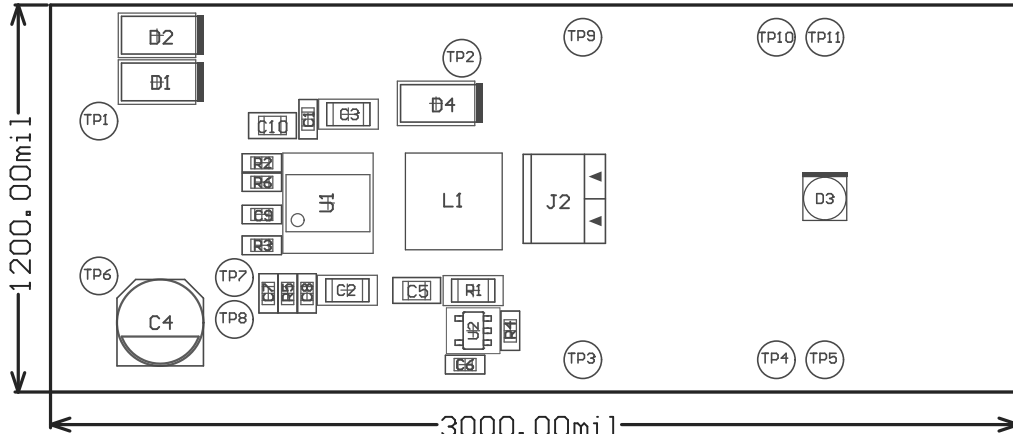
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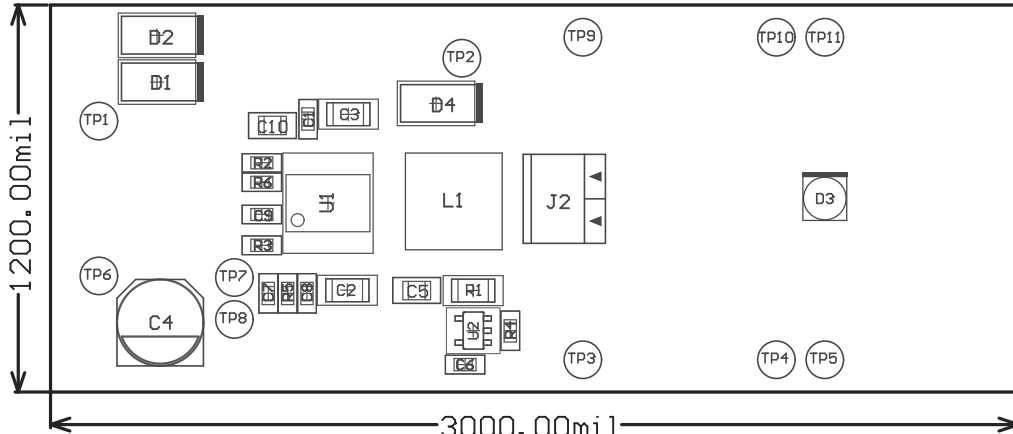
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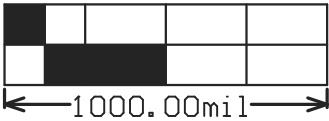
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 ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



1200.00mil

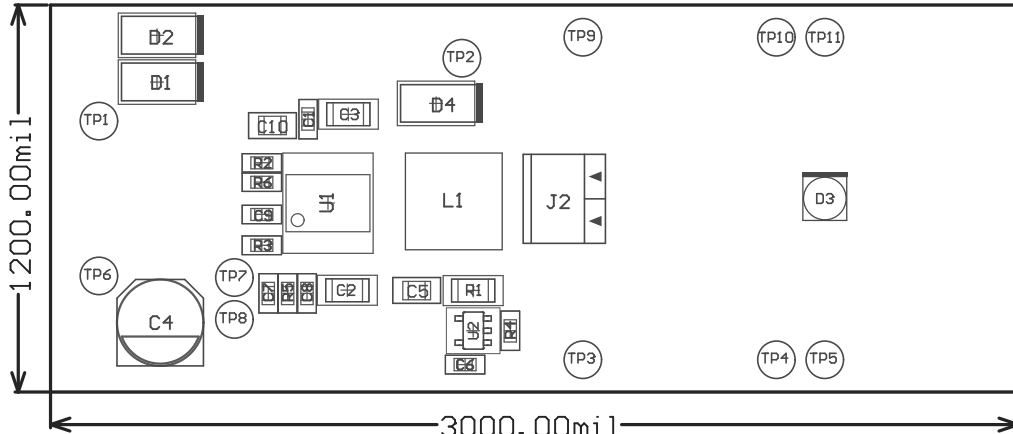
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
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ASSEMBLY VARIANT: [No Variations]



1200.00mil

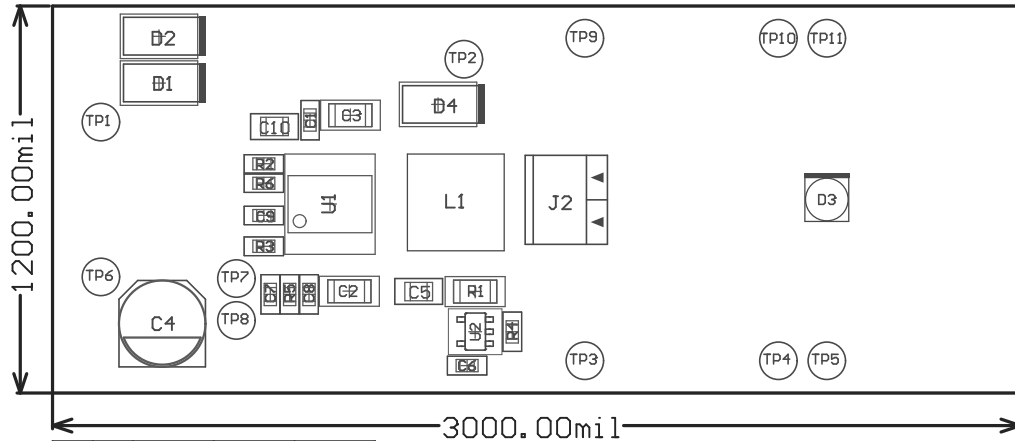
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1000.00mil

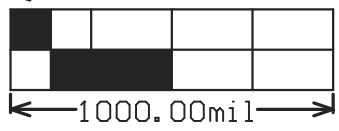
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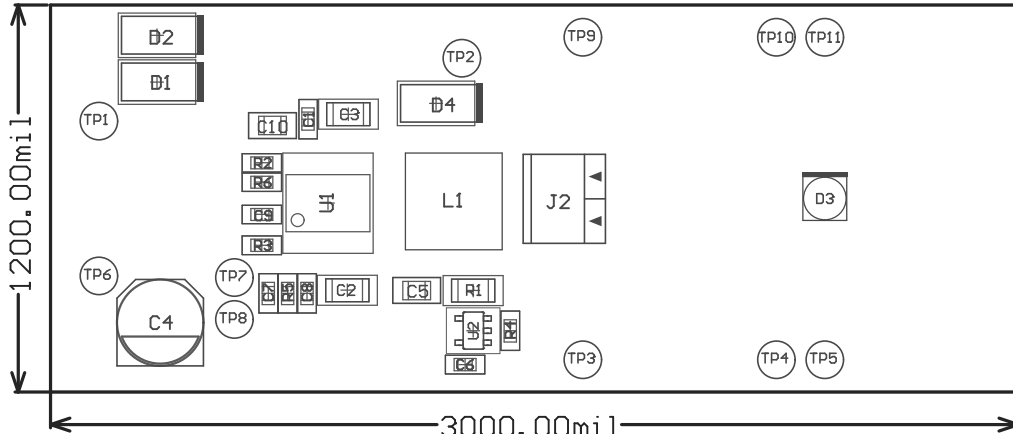
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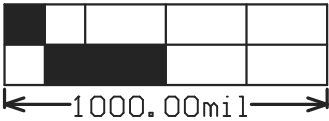
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1200.00mil

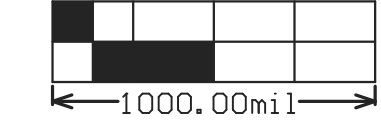
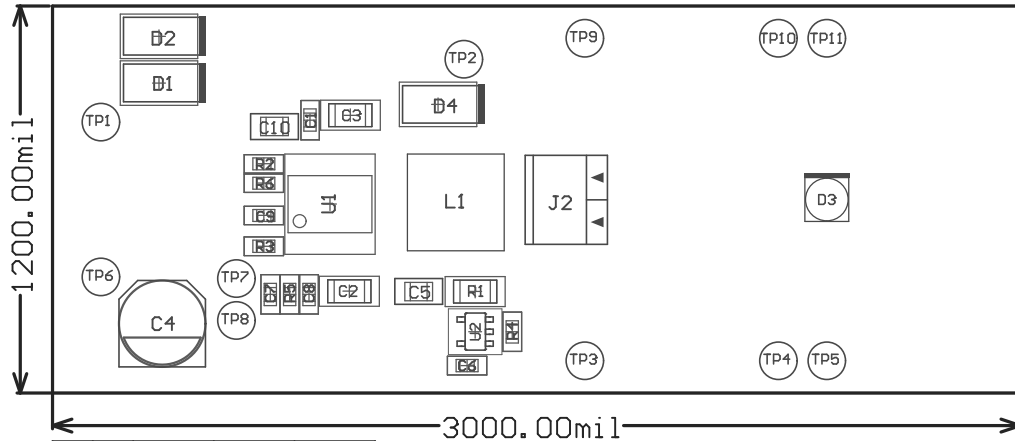
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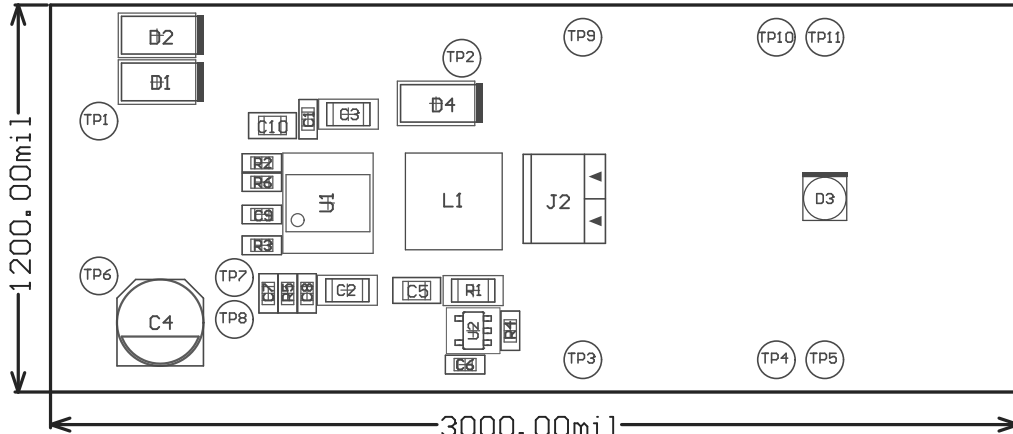
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ASSEMBLY VARIANT: [No Variations]



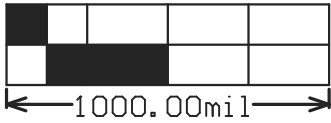
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 ASSEMBLY VARIANT: [No Variations]



1200.00mil

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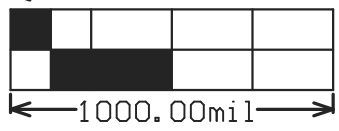
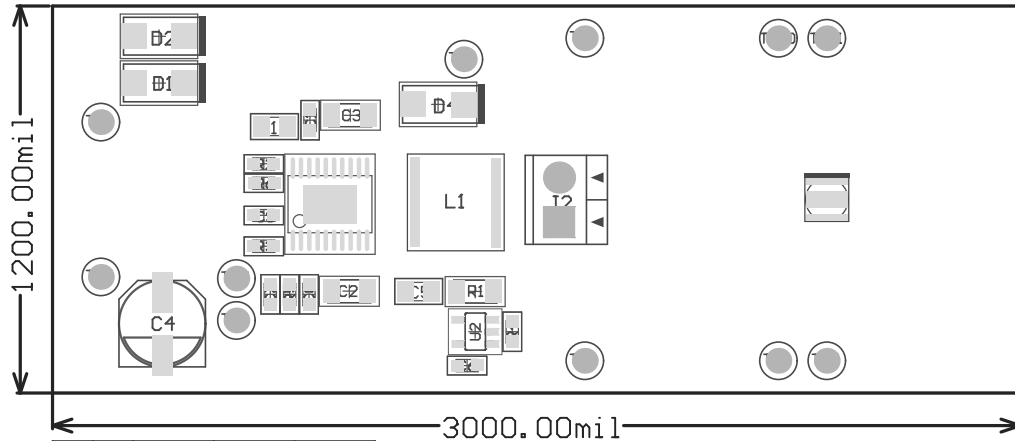


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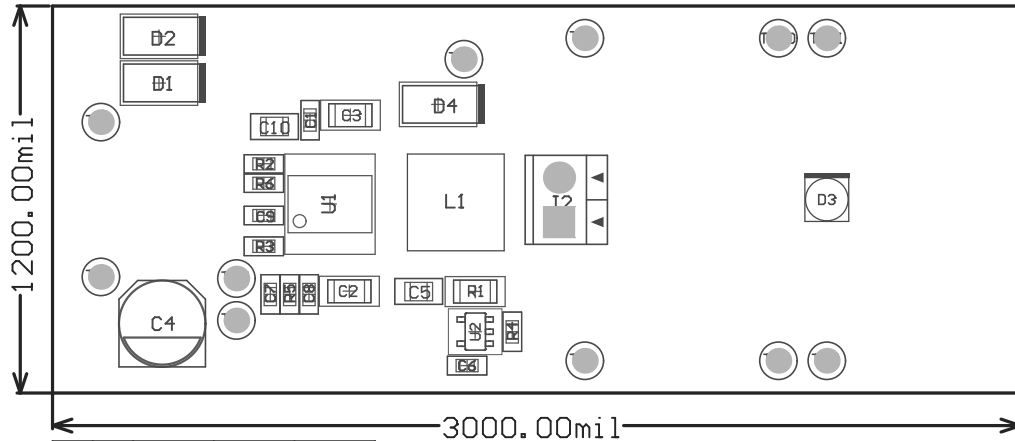
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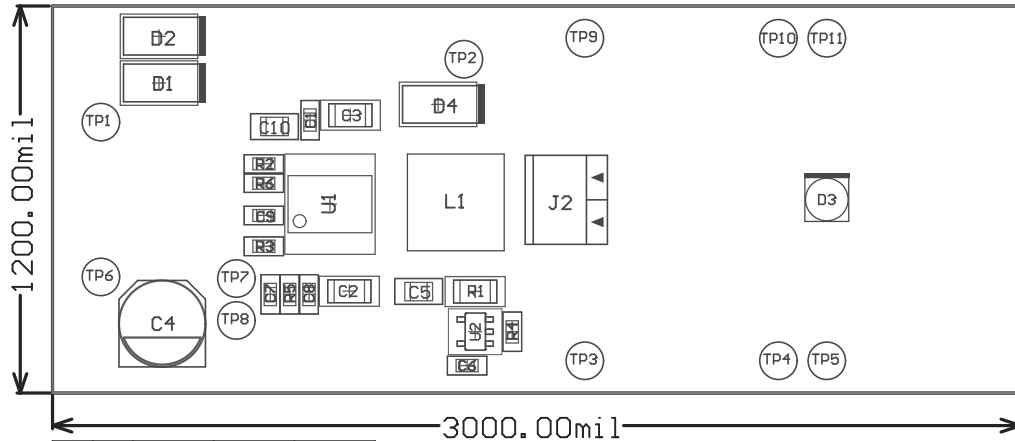
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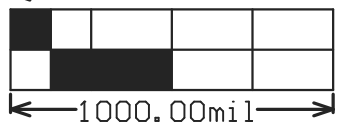
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 ASSEMBLY VARIANT: [No Variations]



1200.00mil

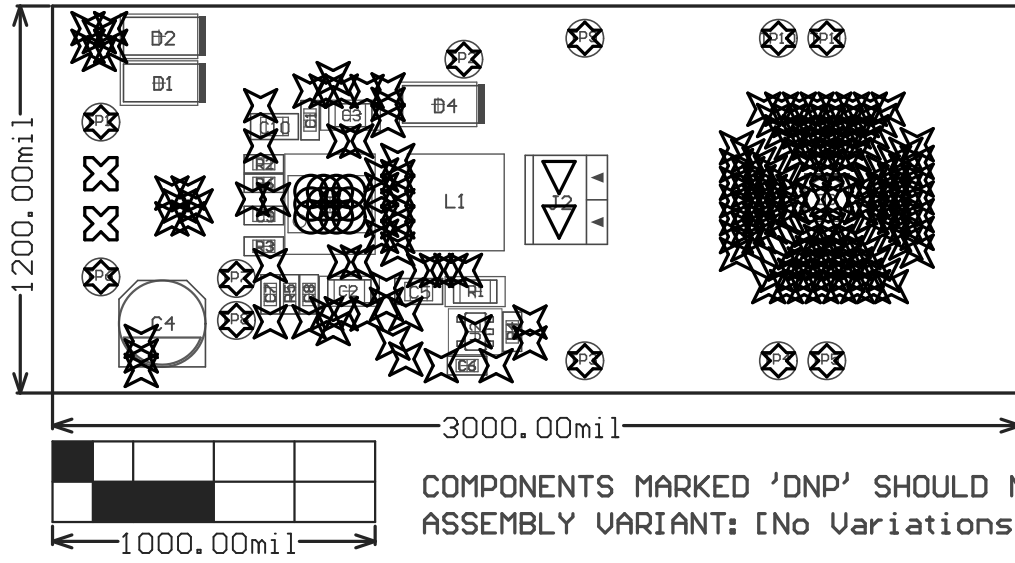
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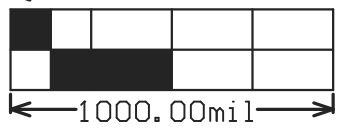
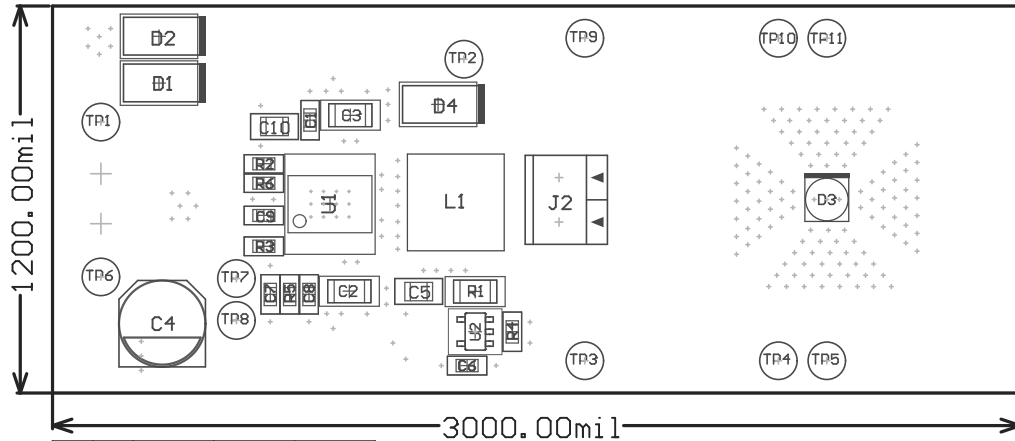
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 ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



| Symbol | Quantity  | Finished Hole Size | Plated | Hole Type |
|--------|-----------|--------------------|--------|-----------|
| ○      | 12        | 7.87mil (0.200mm)  | PTH    | Round     |
| ✖      | 186       | 12.00mil (0.305mm) | PTH    | Round     |
| ☆      | 11        | 40.00mil (1.016mm) | PTH    | Round     |
| ▽      | 2         | 50.00mil (1.270mm) | PTH    | Round     |
| ⊗      | 2         | 65.00mil (1.651mm) | PTH    | Round     |
|        | 213 Total |                    |        |           |

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. BOARD SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED  
 ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED  
 ASSEMBLY VARIANT: [No Variations]

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